

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD80N04S3-06	**Issued**	24. February 2022
MA#	MA005708750		
Package	PG-TO252-3-11	**Weight***	372.50 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.047	0.82	0.82	8181	8181
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		578	
	non noble metal	copper	7440-50-8	215.017	57.72	57.80	577223	577974
wire	non noble metal	aluminium	7429-90-5	5.908	1.59	1.59	15860	15860
encapsulation	inorganic material	zincoxide	1314-13-2	1.225	0.33		3287	
	miscellaneous	miscellaneous	-	6.123	1.64		16437	
	plastics	epoxy resin	-	18.368	4.93		49310	
	inorganic material	silicondioxide	60676-86-0	96.739	25.97	32.87	259702	328736
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10040	10040
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.055	0.01		148	
	noble metal	silver	7440-22-4	0.069	0.02		185	
	non noble metal	lead	7439-92-1	2.638	0.71	0.74	7081	7414
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51483	51550
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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